

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S4	1	("6884634").PN.	US-PGPUB; USPAT	OR	ON	2005/12/09 11:43
S7	49	("3556879" "3559281" "3701696" "3811975" "3869313").PN. OR ("3923567"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/09 12:16
S8	4	("3923567" "5100501" "5426061" "5840590").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/09 13:37
S9	2	("6054373").URPN.	USPAT	OR	ON	2005/12/09 13:38
S10	54	("3009841" "3041226" "3128213" "3266961" "3342652" "3436286" "3615955" "3888053" "3923567" "4144099").PN. OR ("4276114").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/09 13:48
S11	61	("3579815" "3701696" "3723053" "3856472" "3874936" "3905162" "3923567" "3929529" "3997368" "4018626" "4042419" "4069068").PN. OR ("4144099").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/09 13:56
S12	11	("4144099" "4231809" "4732874" "4878988" "4994399" "5272119" "6008140" "6012970" "6020639" "6022265").PN. OR ("6100167").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/09 14:21
S14	1760	(kobe adj (steel seiko precision)). as.	US-PGPUB; USPAT	OR	ON	2005/12/09 14:55
S2	7	("3923567" "5622875" "5855735" "5885334" "6384415" "6406923" "6451696").PN.	US-PGPUB; USPAT	OR	ON	2005/12/09 14:55
S16	1	("20050092349").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/12/09 15:26
S15	4	("6451696" "6384415" "5855735" "6406923").PN.	US-PGPUB; USPAT	OR	ON	2005/12/09 15:26
S13	129	(suzuki near2 tetsuo takada near2 satoru).in.	US-PGPUB; USPAT	OR	ON	2005/12/09 15:32
S19	35	S14 and (clean\$4 reclaim\$4 recover\$4 reus\$4 etch\$4).clm. and (silicon si wafer semiconductor substrate work adj piece workpiece chip).clm.	US-PGPUB; USPAT	OR	ON	2005/12/09 15:33

S20	37	S18 S19	US-PGPUB; USPAT	OR	ON	2005/12/09 15:34
S21	18	S5 and anneal\$3 not S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 15:38
S6	183	S5 and heat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 15:38
S22	10	("4144099" "4231809" "4732874" "4878988" "4994399" "5272119" "6008140" "6012970" "6020639" "6022265").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/09 15:49
S23	1	("6100167").URPN.	USPAT	OR	ON	2005/12/09 15:51
S26	1181	((216/96) or (216/99)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/09 17:07
S25	762	((216/88) or (216/89)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/09 17:07
S24	2	DE-3939661-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:07
S28	165	(438/473).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/09 17:15
S29	11	("4724171" "4863561" "4885056" "4973563" "5051134" "5181985" "5219613" "5275667" "5288333" "5290361" "5308400").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/09 17:32
S30	15	("5516730").URPN.	USPAT	OR	ON	2005/12/09 17:42

S32	1	jp-07122532-\$.did.	JPO; DERWENT	OR	ON	2005/12/09 17:47
S31	2	jp-2001213694-\$.did.	JPO; DERWENT	OR	ON	2005/12/09 17:47
S34	308	S33 not S28 not S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:53
S33	351	S27 and (heat\$4 anneal\$4 thermal\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:53
S27	461	(438/471).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/09 17:53
S35	35	("3559281" "3905162" "3923567" "4276114" "4663890" "4892612" "5409770" "5538465").PN. OR ("5622875").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/09 18:03
S36	9	("20010039101" "20020086539" "3559281" "3923567" "5233216" "5622875" "5660642" "6406923").PN. OR ("6635500").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/09 18:04
S37	1	("2002/0086539").URPN.	USPAT	OR	ON	2005/12/09 18:05
S38	10	("3923567" "4738056" "5051375" "5131979" "5622875" "5855735" "5981301").PN. OR ("6406923"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/09 18:07
S40	49	("3556879" "3559281" "3701696" "3811975" "3869313").PN. OR ("3923567"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/09 18:08
S39	35	("3559281" "3905162" "3923567" "4276114" "4663890" "4892612" "5409770" "5538465").PN. OR ("5622875").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/09 18:08

S41	26	("4724171" "4863561" "4885056" "4973563" "5051134" "5181985" "5219613" "5275667" "5288333" "5290361" "5308400").PN. OR ("5516730"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/09 18:43
S42	16	("5238500" "5486266" "5516730" "5681397" "5681398").PN. OR ("5932022"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/09 18:49
L7	9	6 and alkali	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 12:50
L6	27	(US-20010039101-\$ or US-20020086539-\$).did. or (US-3923567-\$ or US-4144099-\$ or US-4239661-\$ or US-4276114-\$ or US-4395293-\$ or US-4878988-\$ or US-4885056-\$ or US-4954189-\$ or US-5131979-\$ or US-5290361-\$ or US-5516730-\$ or US-5622875-\$ or US-5855735-\$ or US-5885334-\$ or US-5899744-\$ or US-5932022-\$ or US-6054373-\$ or US-6100167-\$ or US-6384415-\$ or US-6406923-\$ or US-6451696-\$ or US-6635500-\$ or US-6706636-\$ or US-6884634-\$ or US-6902988-\$).did.	US-PGPUB; USPAT	OR	ON	2005/12/11 12:50
L8	9	("2676955" "2774759" "3503890" "3553143" "3980587").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/11 12:58
S5	502	(438/4).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/11 13:01
L12	1877	L10 L11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 13:01
L11	1181	((216/96) or (216/99)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/11 13:01

L10	762	((216/88) or (216/89)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/11 13:01
S18	9	S13 and (clean\$4 reclaim\$4 recover\$4 reus\$4 etch\$4).clm. and (silicon si wafer semiconductor substrate work adj piece workpiece chip).clm.	US-PGPUB; USPAT	OR	ON	2005/12/11 13:03
L14	260	13 and (heat\$4 anneal\$4 thermal\$4 bak\$4)	US-PGPUB; USPAT	OR	ON	2005/12/11 13:05
L17	7	16 not 15	US-PGPUB; USPAT	OR	ON	2005/12/11 13:08
L16	23	13 and (alkali with (carbonate hydroxide))	US-PGPUB; USPAT	OR	ON	2005/12/11 13:08
L15	16	14 and (alkali with (carbonate hydroxide))	US-PGPUB; USPAT	OR	ON	2005/12/11 13:08
L18	10	("3951728" "4031667" "4344260" "4581103" "4588473" "5180469" "5225235" "5316620" "5447890" "5494862").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/11 13:13
L21	5206	(reclaim\$4 recover\$4 reus\$4) near5 (silicon si wafer semiconductor substrate work adj piece workpiece chip)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 13:16
L20	1886	(reclaim\$4 recover\$4 reus\$4) near5 (silicon si wafer semiconductor substrate work adj piece workpiece chip)	USOCR	OR	ON	2005/12/11 13:16
L19	37	(reclaim\$4 recover\$4 reus\$4) with (silicon si wafer semiconductor substrate work adj piece workpiece chip) and 12	US-PGPUB; USPAT	OR	ON	2005/12/11 13:16
L13	410	(clean\$4 reclaim\$4 recover\$4 reus\$4) with (silicon si wafer semiconductor substrate work adj piece workpiece chip) and 12	US-PGPUB; USPAT	OR	ON	2005/12/11 13:16
L23	27	(reclaim\$4 recover\$4 reus\$4) near5 (silicon si wafer semiconductor substrate work adj piece workpiece chip) and (heat\$4 thermal\$4 anneal\$4) and (polish\$4 abrad\$4 grind\$4) and (etch\$4 clean\$4 remov\$4)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 13:17

L22	163	(reclaim\$4 recover\$4 reus\$4) near5 (silicon si wafer semiconductor substrate work adj piece workpiece chip) and (heat\$4 thermal\$4 anneal\$4) and (polish\$4 abrad\$4 grind\$4) and (etch\$4 clean\$4 remov\$4)	USOCR	OR	ON	2005/12/11 13:24
L24	22	(etch\$4 clean\$4) with (silicon wafer semiconductor si) same (((alkali sodium na potassium k) adj (hydroxide oh)) and ((alkali sodium na potassium k) adj (carbonate "co.sub.3"))))	US-PGPUB; USPAT	OR	ON	2005/12/11 13:26
L25	30	("4116714" "4261791" "4964919" "5049200" "5051134" "5078801" "5129955" "5176756" "5290361" "5308400" "5340437" "5464480" "5470393" "5487398" "5489557" "5498293" "5505785" "5509970" "5516730" "5560857" "5580846" "5593505" "5626681" "5635463" "5637151" "5662743" "5662769" "5665168" "5704987" "5759971").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/11 13:32
L28	32	(US-20010039101-\$ or US-20020086539-\$ or US-20040108297-\$).did. or (US-3923567-\$ or US-4144099-\$ or US-4239661-\$ or US-4276114-\$ or US-4395293-\$ or US-4878988-\$ or US-4885056-\$ or US-4954189-\$ or US-5131979-\$ or US-5290361-\$ or US-5516730-\$ or US-5622875-\$ or US-5855735-\$ or US-5885334-\$ or US-5899744-\$ or US-5932022-\$ or US-6054373-\$ or US-6100167-\$ or US-6384415-\$ or US-6406923-\$ or US-6451696-\$ or US-6635500-\$ or US-6706636-\$ or US-6884634-\$ or US-6902988-\$ or US-5882539-\$).did. or (US-6451218-\$ or US-6197611-\$ or US-5837662-\$).did.	US-PGPUB; USPAT	OR	ON	2005/12/11 13:45
L29	2	28 and tmah	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 13:46